

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2022 to Q4/2023

Based on structural similarity

	User Part Number						
	PMEG3020EJ-Q						
oratory	Part Description						
	Nexperia DHAM	Schottky					
bility labs	SMD package						
C-Q101 Test	Test Conditions	Duration	# Lots	# Quantity	# Rejects		
TEST							
Pre- and Post-Stress							
Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
	JESD22-A113						
	Bake Tamb = 125 °C	24 hours					
	•						
Preconditioning	Reflow soldering	3 cycles	1514	64430	0		
	MIL-STD-750-1						
HTRB							
High Temperature Reverse							
Bias	reverse voltage <sup>[1]</sup>	1000 hours	206	9320	0		
TC	JECD22 A104						
		1000 evelee	211	14000	0		
remperature Cycling	-03 C to filliax, flot to exceed 150 C	1000 cycles	311	14080	U		
UHAST	IFSD22-A118						
Unbiased HAST	Tamb = 130 °C, RH = 85 %		311	14080	0		
	IFSD22-Δ102	- 96 hours					
AC							
Autoclave							
H3TRB	JESD22-A101						
	Tamb = 85 °C, RH = 85%, VR = 80 % of						
	rated reverse voltage <sup>[1], [2]</sup>	1000 hours	311	14080	0		
	MIL-STD-750 Method 1037						
IOL	ton = toff, devices powered to insure $\Delta T_i$ =						
Intermittent Operating Life		1000 hours	312	14120	0		
RSH	JESD22-A111						
Resistance to Solder Heat	260 °C ± 5 °C	10 s	269	8070	0		
SD							
Solderability	J-STD-002		222	6660	0		
ı	pc Preconditioning  HTRB High Temperature Reverse Bias  TC Temperature Cycling  UHAST Unbiased HAST  AC Autoclave  H3TRB High Humidity High Temperature Reverse Bias  IOL Intermittent Operating Life  RSH Resistance to Solder Heat SD	Part Description Nexperia DHAM SMD package  C-Q101 Test Test Conditions  TEST Pre- and Post-Stress Electrical Test  Pec and Post-Stress Electrical Test  Tamb = 25 °C  JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Preconditioning  MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage <sup>[1]</sup> TC JESD22-A104 Temperature Reverse Bias  TC JESD22-A104 Temperature Cycling  JESD22-A118 Unbiased HAST  JESD22-A118 Unbiased HAST  JESD22-A110 AC Autoclave  JESD22-A102 AC Autoclave  JESD22-A102 AC Autoclave  Pressure = 205 kPa (29.7 psia)  MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles  RSH Resistance to Solder Heat  JESD22-A111 260 °C ± 5 °C  SD	Part Description   Nexperia DHAM   Schottky	Part Description   Nexperia DHAM   Schottky	Part Description   Nexperia DHAM   Schottky   SMD package   SMD package   SChottky   SMD package   SMD package   SChottky   SMD package   SMD package		

<sup>[1]</sup> The physical limitations of Schottky diodes have to be considered (thermal runaway).

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)
Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

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<sup>[2]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.